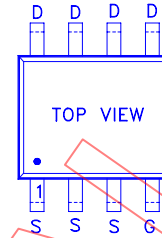
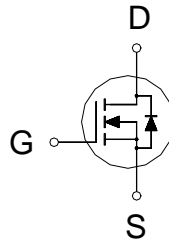


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30	15mΩ	11A



G : GATE
D : DRAIN
S : SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	$T_C = 25\text{ °C}$	I_D	11	A
	$T_C = 70\text{ °C}$		7.5	
Pulsed Drain Current ¹		I_{DM}	48	
Power Dissipation	$T_C = 25\text{ °C}$	P_D	2.5	W
	$T_C = 70\text{ °C}$		2.0	
Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		50	°C / W

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_C = 25\text{ °C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	3.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 55\text{ °C}$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$		17.5	24	mΩ
		$V_{GS} = 10V, I_D = 11A$		12.5	15	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 11A$		18		S

DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		960	1200	pF
Output Capacitance	C_{oss}			150		
Reverse Transfer Capacitance	C_{rss}			120		
Gate Resistance	R_g	$V_{GS} = 15mV, V_{DS} = 0V, f = 1MHz$		1.5		Ω
Total Gate Charge ² (10V)	Q_g	$V_{DS} = 0.5V_{(BR)DSS}, V_{GS} = 10V,$ $I_D = 11A$		17	26	nC
Total Gate Charge ² (4.5V)	Q_g			10	12	
Gate-Source Charge ²	Q_{gs}			3.1		
Gate-Drain Charge ²	Q_{gd}			6.5		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 15V,$ $I_D \cong 1A, V_{GS} = 10V, R_{GEN} = 3\Omega$		5.5	7	nS
Rise Time ²	t_r			6.5	8	
Turn-Off Delay Time ²	$t_{d(off)}$			20	26	
Fall Time ²	t_f			5	7	
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25^\circ C$)						
Continuous Current	I_S				4.5	A
Pulsed Current ³	I_{SM}				9	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			1.1	V
Reverse Recovery Time	t_{rr}	$I_F = 4.5A, di_F/dt = 100A / \mu S$		20	25	nS

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

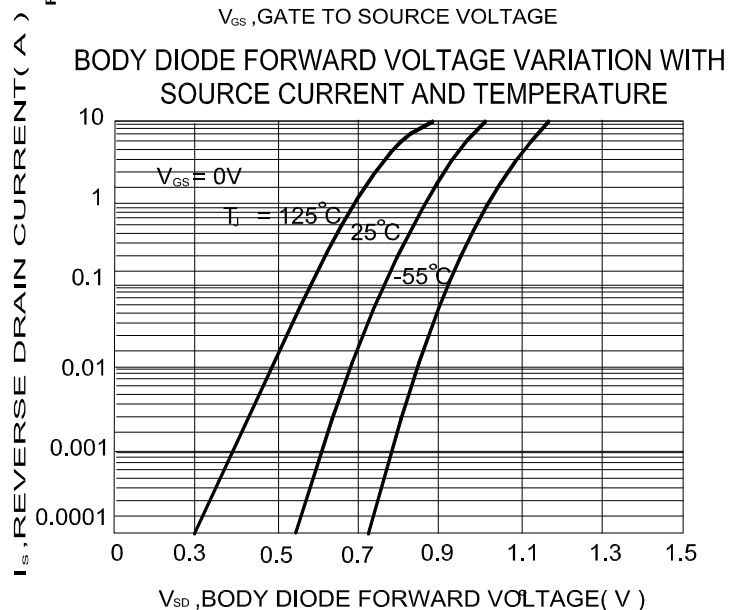
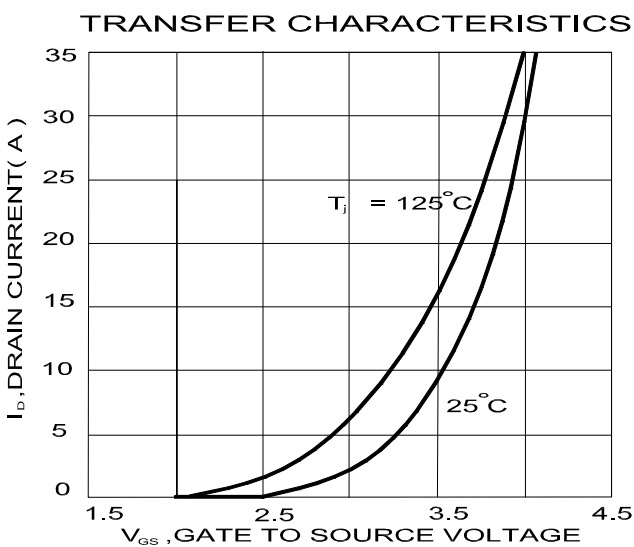
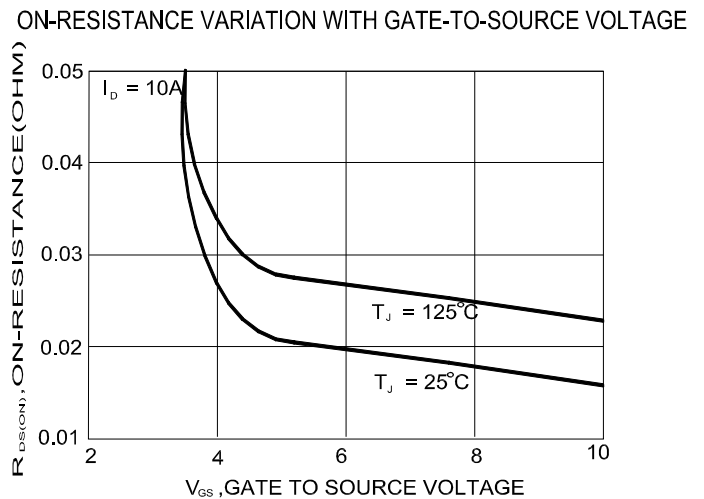
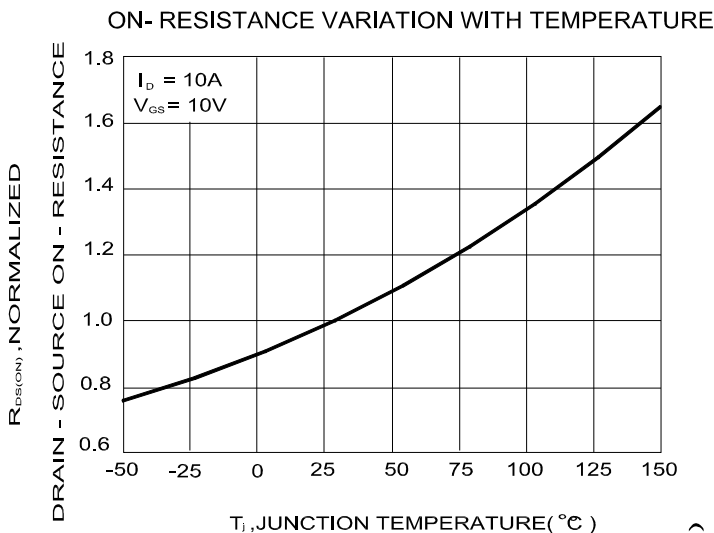
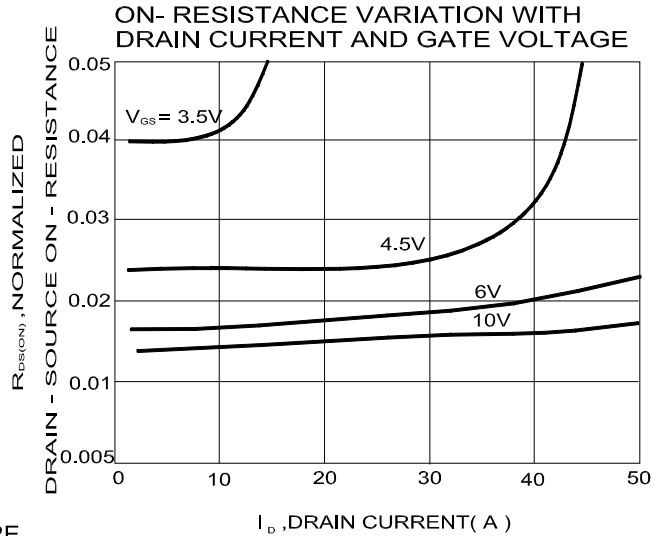
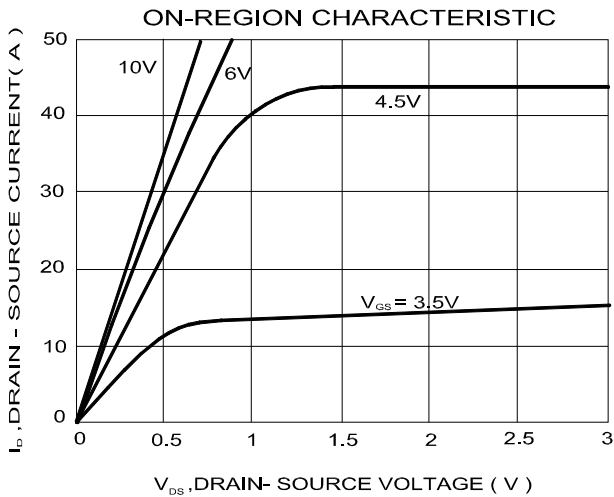
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

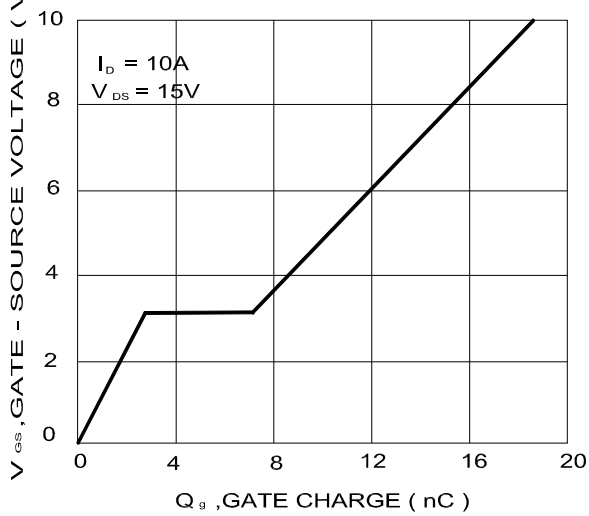
REMARK: THE PRODUCT MARKED WITH "P1503BVG", DATE CODE or LOT #

Orders for parts with Lead-Free plating can be placed using the PXXXXXXG parts name.

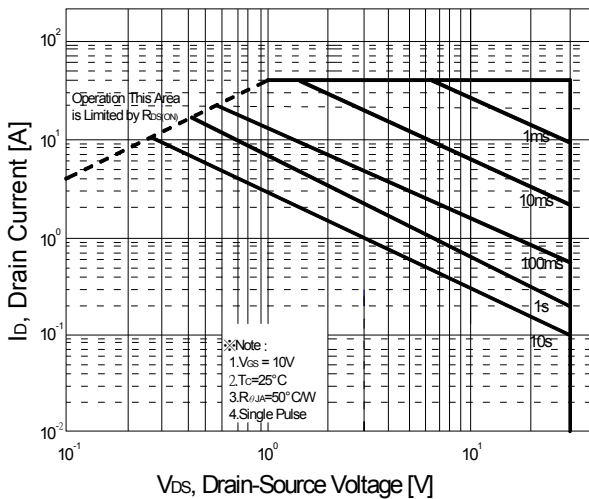
TYPICAL PERFORMANCE CHARACTERISTICS



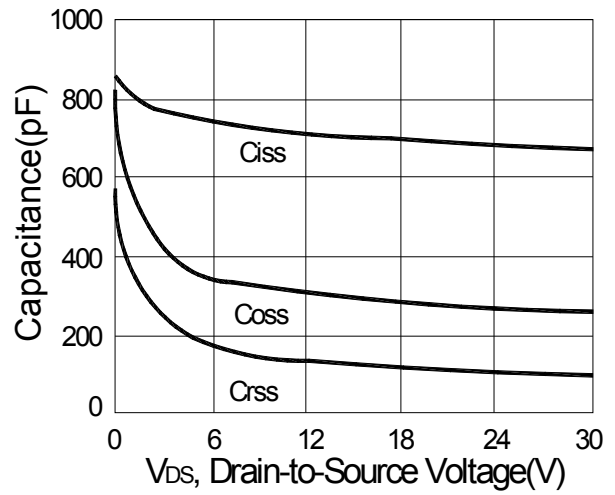
GATE CHARGE CHARACTERISTICS



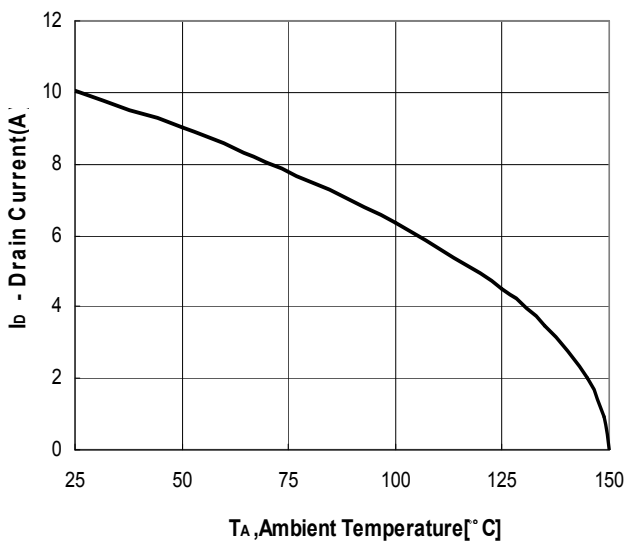
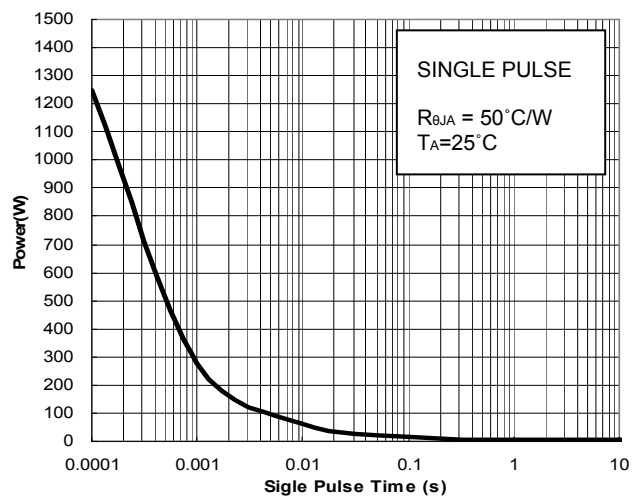
Maximum Safe Operating Area

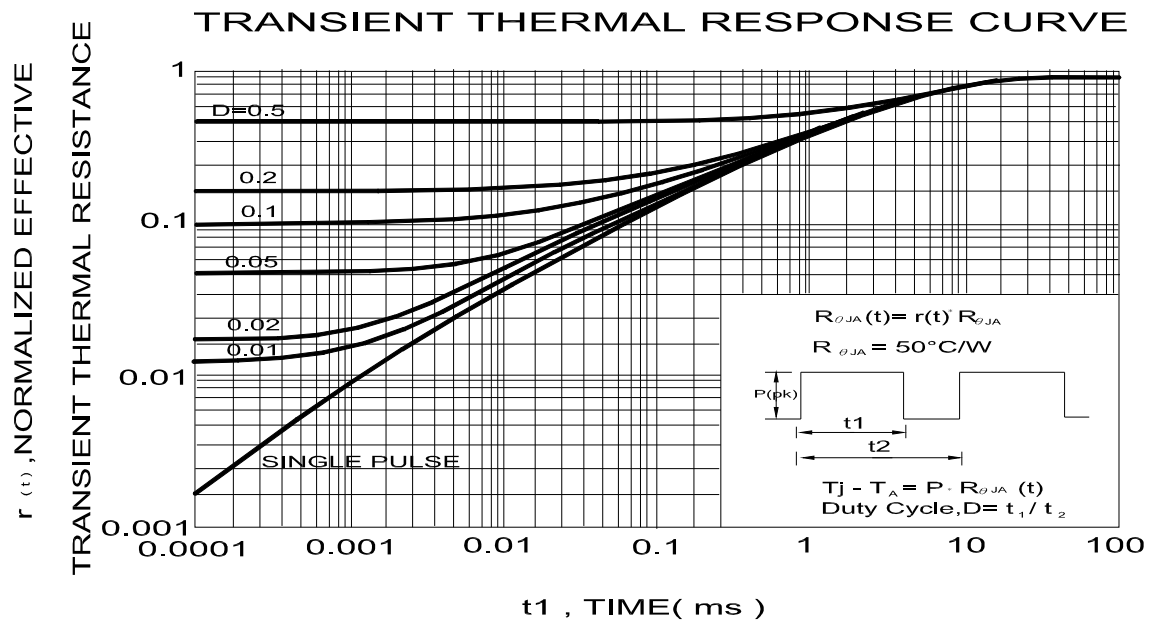


CAPACITANCE CHARACTERISTICS



Single Pulse Maximum Power dissipation





SOIC-8(D) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.70	4.90	5.10	H	0.40	0.715	0.83
B	3.70	3.90	4.10	I	0.19	0.22	0.26
C	5.80	6.00	6.20	J	0.25	0.375	0.5
D	0.33	0.445	0.51	K	0°	4°	8°
E		1.27		L			
F	1.20	1.375	1.62	M			
G	0.08	0.175	0.28	N			

